

Special issue on

Advances in Radio Frequency Identification (RFID) chips

CALL FOR PAPERS

Submission Deadline: August 26, 2023

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Papers are published upon acceptance, regardless of the Special Issue publication date.

In our journal *Chip Design and Manufacturing*, a special issue is calling for papers about Radio Frequency Identification (RFID) chips.

The manufacture of integrated circuits (ICs), widely known as “chips”, is probably the most amazing manufacturing process the world has ever seen. A piece of silicon smaller than a postage stamp can contain billions of transistors, which act like on/off switches and are the basic active components on the chip.

Radio Frequency Identification (RFID) is a form of wireless communication that incorporates the use of electromagnetic or electrostatic coupling in the radio frequency portion of the electromagnetic spectrum to uniquely identify an object, animal, or person. RFID chips are tiny computer chips attached to a miniature antenna that can be placed on or inside a physical object. They are used in a wide variety of applications that require “contactless” authentication, including toll booths, transit passes, passports, and contactless entrance keys. The lifetime of an RFID chip depends on many factors. If the antenna and chip are exposed to harsh chemicals or high heat, it may not last very long. However, under normal conditions, most tags can operate for 20 years or more.

This special issue invites theoretical and applied cutting-edge research on RFID chips, such as **approaches for security, privacy, and trust management in the diverse and long list of RFID chips application, the advanced techniques involved, RFID sensors, and RFID components**. Potential topics include but are not limited to the ones mentioned above.